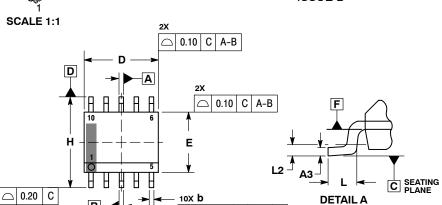
2X 5 TIPS

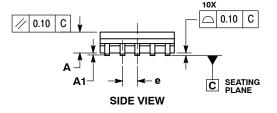




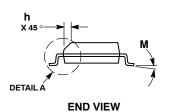
DATE 26 NOV 2013



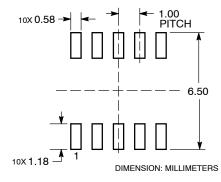
⊕ 0.25 M C A-B D



TOP VIEW



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- ASMIE 114:301, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE PROTRUSION
- AT MAXIMUM MATERIAL CONDITION.

 SHALL BE 0.10mm TOTAL IN EXCESS OF 'b'

 AT MAXIMUM MATERIAL CONDITION.

 DIMENSIONS D AND E DO NOT INCLUDE

 MOLD FLASH, PROTRUSIONS, OR GATE

 BURRS. MOLD FLASH, PROTRUSIONS, OR

 GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
- DIMENSIONS A AND B ARE TO BE DETERM-INED AT DATUM F.
- INED AT DATUM F. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS			
DIM	MIN	MIN MAX		
Α	1.25	1.75		
A1	0.10	0.25		
A3	0.17	0.25		
b	0.31	0.51		
D	4.80	5.00		
Е	3.80	4.00		
е	1.00 BSC			
Н	5.80	6.20		
h	0.37	0.37 REF		
L	0.40	0.80		
L2	0.25 BSC			
М	0°	8°		

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

Α = Assembly Location = Wafer Lot L

Υ = Year W = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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NEW STANDARD:			
DESCRIPTION:	SOIC-10 NB		PAGE 1 OF 2



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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY M. RAMOS.	06 JUL 2010
Α	CHANGED DIMENSION A MIN FROM 1.35 TO 1.25. REQ. BY HB TAN.	25 APR 2011
В	CHANGED DIMENSION L MAX FROM 1.27 TO 0.80 MM. REQ. BY C. TAN.	26 NOV 2013

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